



CLAIM AMENDMENT



AMENDMENT B
(37 C.F.R. 1.111)

IN THE CLAIMS:

Please amend claims 9 and 14.

Please cancel claim 10-12.

The claims are included on separate sheets herein.

1.- 8. (Previously canceled)

9. (Currently Amended) The colloid silica slurry wherein it does not have a bad influence, such as corrosion, to a silicon wafer and wiring material on a silicon wafer and inhibits growth of microbes, and whereof preserving stability is high because stability of a particle diameters of colloidal particle is superior and using for a long period continuously is possible, and said colloidal silica slurry is comprised by adding hydrogen peroxide 5 to 100 ppm to lowered metal silica slurry, which metal content is 1 ppm or less and produced from silicate ester, and the pH of colloidal silica slurry is 6.0 to 8.0 and content of colloidal silica is 0.05 ~ 50 weight % ~~hydrogen peroxide from 5 to 100 ppm is added and pH is from 6.0 to 8.0.~~

10. (Canceled)

11. (Canceled)

12. (Canceled)

13. (Previously Added) The colloidal silica slurry as claimed in claim 9, wherein pH is from 6.5 to 7.5.

14. (Currently Amended) The colloidal silica slurry as claimed in claim 9, wherein additional quantity of said hydrogen peroxide is from 10 to 50 ppm.

15. (Previously Added) The colloidal silica slurry as claimed in claim 9, wherein an average particle diameter of said colloidal silica is from 5 to 300 nm.

16. (Previously Amended) The colloidal silica slurry as claimed in claim 9, wherein an average particle diameter of said colloidal silica is from 10 to 250 nm.